

POWER MODULE

ABSTRACT OF THE DISCLOSURE

A power module includes a substrate, a first sub-module, a second sub-module and a circuit board. The semiconductor switches and the diodes of the first sub-module and the second sub-module are embedded within insulation layers. Consequently, the first sub-module and the second sub-module are formed as a high-voltage-side switching element and a low-voltage-side switching element of a bridge circuit. The first sub-module and the second sub-module are disposed on a first surface of a substrate. An electrode of the first sub-module and some electrodes of the second sub-module are electrically connected with corresponding conducting parts of a circuit board. A heat sink is disposed on a second surface of the substrate.

[Figure 1]